# 1N6382 - 1N6389 Series (ICTE-10C - ICTE-36C, MPTE-8C - MPTE-45C)

# **1500 Watt Peak Power** Mosorb<sup>™</sup> Zener Transient **Voltage Suppressors**

## **Bidirectional\***

Mosorb devices are designed to protect voltage sensitive components from high voltage, high-energy transients. They have excellent clamping capability, high surge capability, low zener impedance and fast response time. These devices are ON Semiconductor's exclusive, cost-effective, highly reliable Surmetic<sup>™</sup> axial leaded package and are ideally-suited for use in communication systems, numerical controls, process controls, medical equipment, business machines, power supplies and many other industrial/consumer applications, to protect CMOS, MOS and Bipolar integrated circuits.

#### **Specification Features:**

- Working Peak Reverse Voltage Range 8 V to 45 V
- Peak Power 1500 Watts @ 1 ms
- ESD Rating of Class 3 (>16 KV) per Human Body Model
- Maximum Clamp Voltage @ Peak Pulse Current
- Low Leakage < 5 μA Above 10 V
- Response Time is Typically < 1 ns

#### **Mechanical Characteristics:**

40UR C **CASE:** Void-free, transfer-molded, thermosetting plastic FINISH: All external surfaces are corrosion resistant and leads are readily solderable

### MAXIMUM LEAD TEMPERATURE FOR SOLDERING PURPOSES:

230°C, 1/16" from the case for 10 seconds **POLARITY:** Cathode band does not imply polarity **MOUNTING POSITION:** Any

#### MAXIMUM RATINGS

Rating	Symbol	Value	Unit					
Peak Power Dissipation (Note 1) @ T <sub>L</sub> ≤ 25°C	P <sub>PK</sub>	1500	Watts					
Steady State Power Dissipation @ $T_L \le 75^{\circ}$ C, Lead Length = 3/8" Derated above $T_L = 75^{\circ}$ C	P <sub>D</sub>	5.0 20	Watts mW/°C					
Thermal Resistance, Junction-to-Lead	$R_{\thetaJL}$	20	°C/W					
Operating and Storage Temperature Range	T <sub>J</sub> , T <sub>stg</sub>	– 65 to +175	°C					

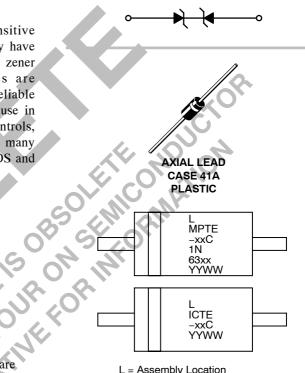
1. Nonrepetitive current pulse per Figure 4 and derated above  $T_A = 25^{\circ}C$ per Figure 2.

\*Please see 1N6373 - 1N6381 (ICTE-5 - ICTE-36, MPTE-5 - MPTE-45) for Unidirectional Devices



## **ON Semiconductor®**

http://onsemi.com



L = Assembly Location MPTE-xxC = ON Device Code ICTE-xxC = ON Device Code 1N63xx = JEDEC Device Code YY = Year WW = Work Week

#### **ORDERING INFORMATION**

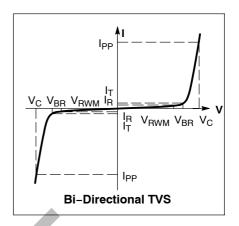
Device	Package	Shipping			
MPTE-xxC	Axial Lead	500 Units/Box			
MPTE-xxCRL4	Axial Lead	1500/Tape & Reel			
ICTE-xxC*	Axial Lead	500 Units/Box			
ICTE-xxCRL4	Axial Lead	1500/Tape & Reel			
1N63xx	Axial Lead	500 Units/Box			
1N63xxRL4	Axial Lead	1500/Tape & Reel			

\*ICTE-10C Not Available in 500 Units/Box

#### **ELECTRICAL CHARACTERISTICS**

 $(T_A = 25^{\circ}C \text{ unless otherwise noted})$ 

Symbol	Parameter						
I <sub>PP</sub>	Maximum Reverse Peak Pulse Current						
V <sub>C</sub>	Clamping Voltage @ I <sub>PP</sub>						
V <sub>RWM</sub>	Working Peak Reverse Voltage						
I <sub>R</sub>	Maximum Reverse Leakage Current @ V <sub>RWM</sub>						
V <sub>BR</sub>	Breakdown Voltage @ I <sub>T</sub>						
Ι <sub>Τ</sub>	Test Current						
$\Theta V_{BR}$	Maximum Temperature Variation of VBR						



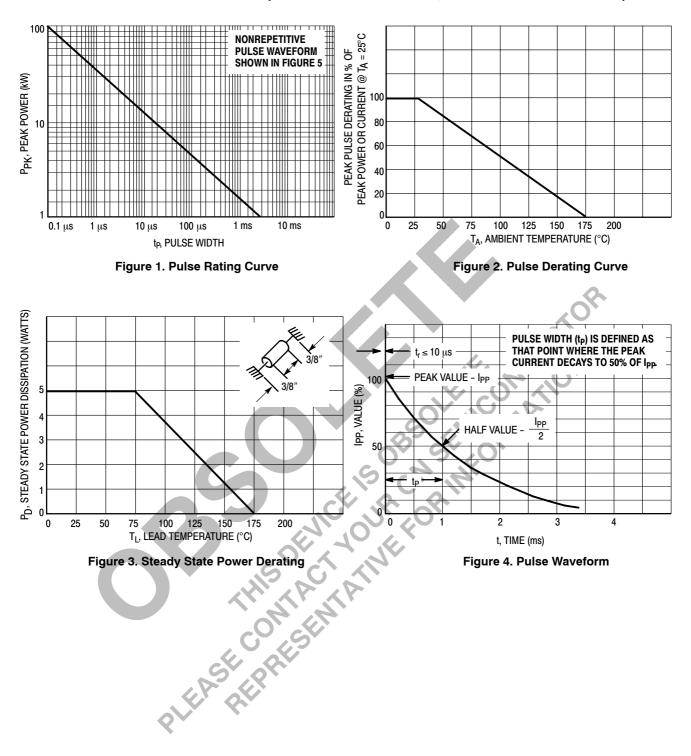
### **ELECTRICAL CHARACTERISTICS** ( $T_A = 25^{\circ}C$ unless otherwise noted)

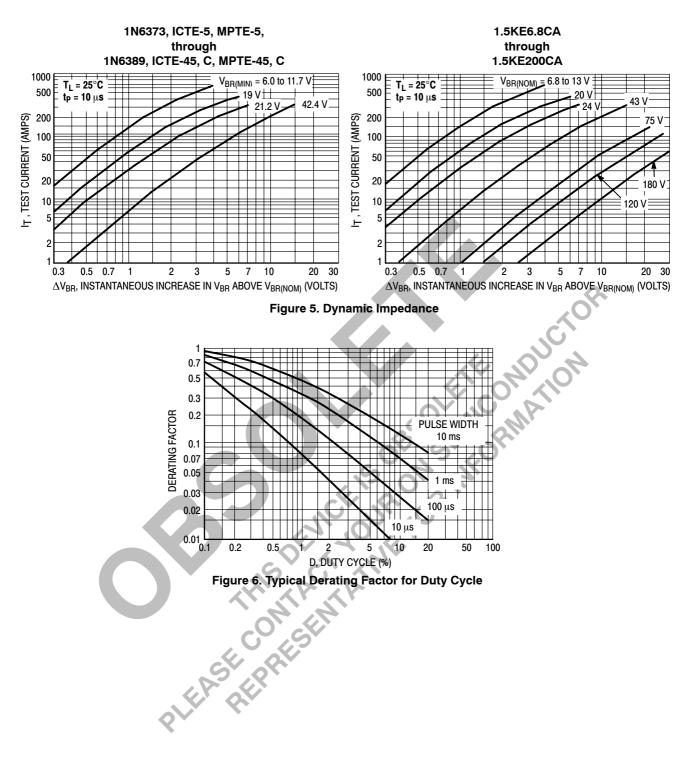
		V <sub>BWM</sub> I <sub>B</sub> @		Breakdown Voltage			V <sub>C</sub> @ I <sub>PP</sub> (Note 4)		V <sub>C</sub> (Volts) (Note 4)			
JEDEC Device (ON Device)	Device Marking	V <sub>RWM</sub> (Note 2) (Volts)	V <sub>RWM</sub>	VBR (Note 3) (Volts)		@ I <sub>T</sub>	Vc	IPP	@ Ipp	@ Ipp	ΘV <sub>BR</sub>	
			<b>(μΑ)</b>	Min	Nom	Max	(mA)	(Volts)	(A)	= 1 A	= 10 A	(mV/°C)
1N6382 (MPTE-8C)	1N6382 MPTE-8C	8.0	25	9.4	-	1	1.0	15	100	11.3	11.5	8.0
1N6383 (MPTE-10C)	1N6383 MPTE-10C	10	2.0	11.7	1		1.0	16.7	90	13.7	14.1	12
1N6384 (MPTE-12C)	1N6384 MPTE-12C	12	2.0	14.1	_	-	1.0	21.2	70	16.1	16.5	14
1N6385 (MPTE-15C)	1N6385 MPTE-15C	15	2.0	17.6	-	Ş	1.0	25	60	20.1	20.6	18
1N6386 (MPTE-18C)	1N6386 MPTE-18C	18	2.0	21.2		-	1.0	30	50	24.2	25.2	21
1N6387 (MPTE-22C)	1N6387 MPTE-22C	22	2.0	25.9		0	1.0	37.5	40	29.8	32	26
1N6388 (MPTE-36C)	1N6388 MPTE-36C	36	2.0	42.4	5		1.0	65.2	23	50.6	54.3	50
1N6389 (MPTE-45C)	1N6389 MPTE-45C	45	2.0	52.9	1.	Ľ.	1.0	78.9	19	63.3	70	60
ICTE-10C* ICTE-12C	ICTE-10C* ICTE-12C	10 12	2.0 2.0	11.7 14.1	<b>0</b> -	-	1.0 1.0	16.7 21.2	90 70	13.7 16.1	14.1 16.5	8.0 12
ICTE-15C ICTE-18C	ICTE-15C ICTE-18C	15 18	2.0 2.0	17.6 21.2	-	-	1.0 1.0	25 30	60 50	20.1 24.2	20.6 25.2	14 18
ICTE-22C ICTE-36C	ICTE-22C ICTE-36C	22 36	2.0 2.0	25.9 42.4	-	-	1.0 1.0	37.5 65.2	40 23	29.8 50.6	32 54.3	21 26

NOTES:

2. A transient suppressor is normally selected according to the maximum working peak reverse voltage (V<sub>RWM</sub>), which should be equal to or greater than the dc or continuous peak operating voltage level.

3. V<sub>BR</sub> measured at pulse test current  $I_T$  at an ambient temperature of 25°C and minimum voltage in V<sub>BR</sub> is to be controlled. 4. Surge current waveform per Figure 4 and derate per Figures 1 and 2. \*Not Available in the 500 Units/Box.





#### **APPLICATION NOTES**

#### **RESPONSE TIME**

In most applications, the transient suppressor device is placed in parallel with the equipment or component to be protected. In this situation, there is a time delay associated with the capacitance of the device and an overshoot condition associated with the inductance of the device and the inductance of the connection method. The capacitance effect is of minor importance in the parallel protection scheme because it only produces a time delay in the transition from the operating voltage to the clamp voltage as shown in Figure 7.

The inductive effects in the device are due to actual turn-on time (time required for the device to go from zero current to full current) and lead inductance. This inductive effect produces an overshoot in the voltage across the equipment or component being protected as shown in Figure 8. Minimizing this overshoot is very important in the application, since the main purpose for adding a transient suppressor is to clamp voltage spikes. These devices have excellent response time, typically in the picosecond range and negligible inductance. However, external inductive effects could produce unacceptable overshoot. Proper circuit layout, minimum lead lengths and placing the suppressor device as close as possible to the equipment or components to be protected will minimize this overshoot.

Some input impedance represented by  $Z_{in}$  is essential to prevent overstress of the protection device. This impedance should be as high as possible, without restricting the circuit operation.

#### DUTY CYCLE DERATING

The data of Figure 1 applies for non-repetitive conditions and at a lead temperature of 25°C. If the duty cycle increases, the peak power must be reduced as indicated by the curves of Figure 6. Average power must be derated as the lead or ambient temperature rises above 25°C. The average power derating curve normally given on data sheets may be normalized and used for this purpose.

At first glance the derating curves of Figure 6 appear to be in error as the 10 ms pulse has a higher derating factor than the 10  $\mu$ s pulse. However, when the derating factor for a given pulse of Figure 6 is multiplied by the peak power value of Figure 1 for the same pulse, the results follow the expected trend.

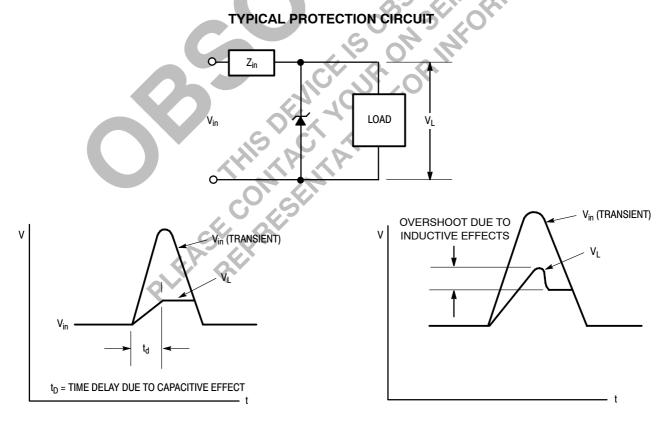


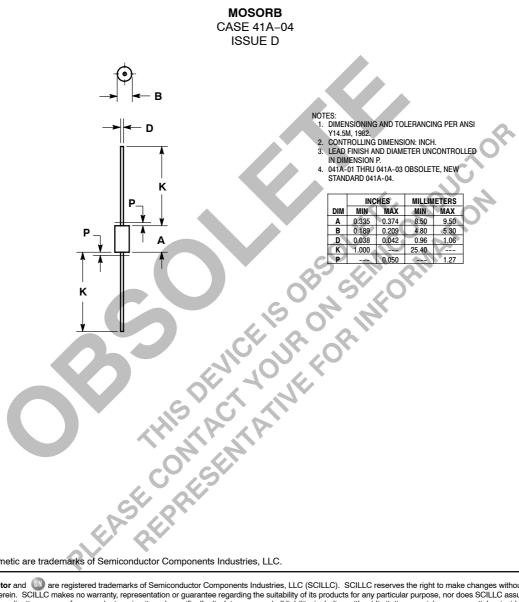
Figure 7.

Figure 8.

**OUTLINE DIMENSIONS** 

# **Transient Voltage Suppressors – Axial Leaded**

# 1500 Watt Peak Power Mosorb



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